

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

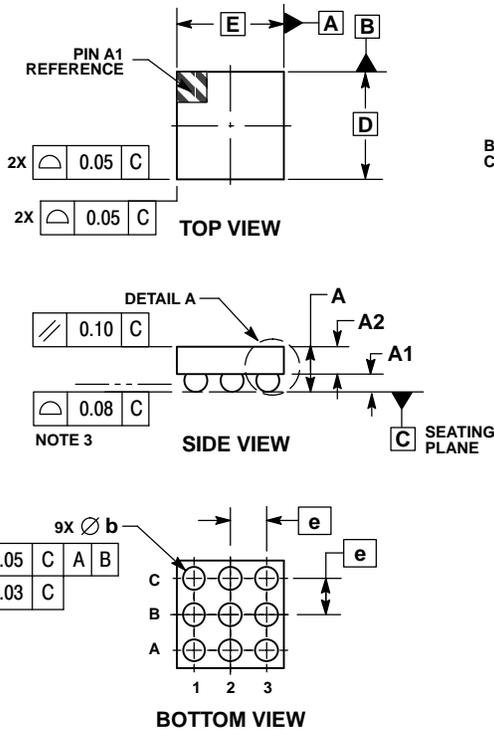
ON Semiconductor®



SCALE 4:1

WLCSP9, 1.19x1.19
CASE 567MD
ISSUE A

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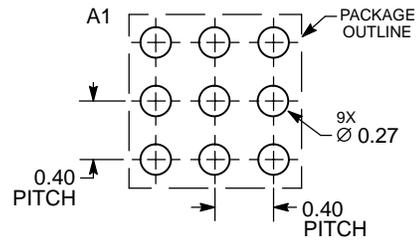


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
4. BACKSIDE COATING IS OPTIONAL.

DIM	MILLIMETERS	
	MIN	MAX
A	—	0.52
A1	0.18	0.22
A2	0.26	0.29
A3	0.000	0.027
b	0.24	0.28
D	1.19 BSC	
E	1.19 BSC	
e	0.40 BSC	

**RECOMMENDED
SOLDERING FOOTPRINT***



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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NEW STANDARD:		
DESCRIPTION:	WLCSP9, 1.19X1.19	PAGE 1 OF 2

